

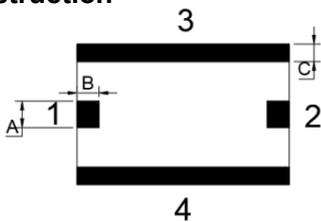
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

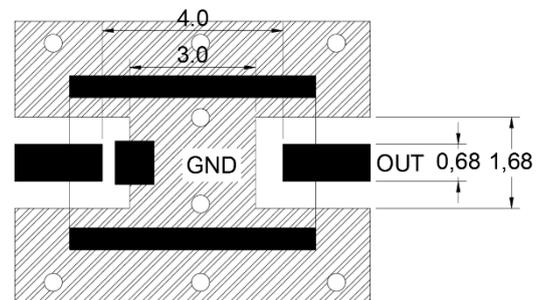
NO.	Parameter	Specifications	Unit
1	Center Frequency (f0)	3150	MHz
2	Band Width	2800-3500	MHz
3	Insertion Loss	≤2.75 (Typical)	dB
4	VSWR	2.0 max.	-
5	Attenuation	≥50@10~2200 MHz ≥40@2200~2400 MHz ≥30@2400~2500 MHz ≥30@3800~3900 MHz ≥40@3900~4000 MHz ≥50@4000-6000 MHz	dB
6	In/Output Impedance	50	(Ω)
7	Input RF Power	2.0 max.	W
<b>Operating &amp; Storage Condition (Component)</b> Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C~ +85°C			
<b>Storage Condition before Soldering (Included packaging material)</b> Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity			

### Construction



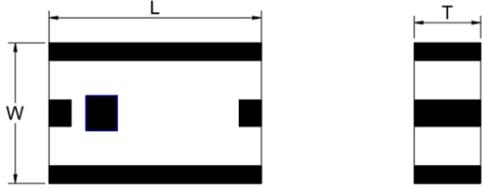
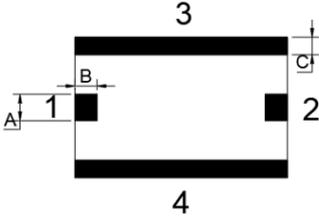
PIN	Connection
1	Input port
2	Output port
3	GND
4	GND

### Mounting Considerations



Unit: mm

### Dimensions

Figure	Symbol	Dimension (mm)
	L	5.00 ± 0.20
	W	3.20 ± 0.20
	T	1.50 ± 0.20
	A	0.60 ± 0.10
	B	0.50 ± 0.10
	C	0.40 ± 0.10

### Typical Electrical Characteristics (T=25°C)

